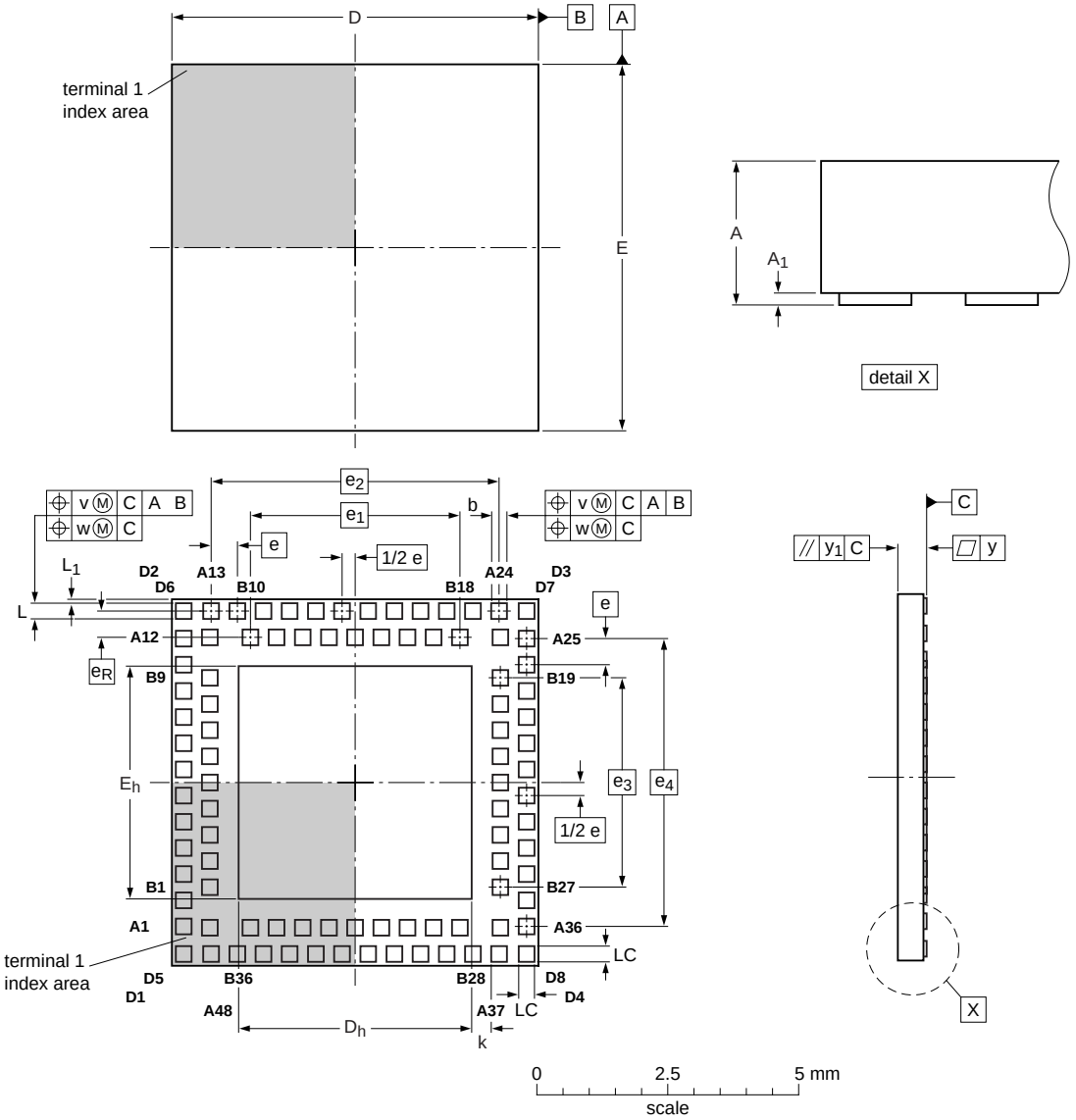
HUQFN92U: plastic thermal enhanced ultra thin quad flat package; no leads; 92 terminals; UTLP based; body 7 x 7 x 0.55 mm **SOT1066-1**



DIMENSIONS (mm are the original dimensions)

UNIT		A	A_1	b	D	D_h	E	E_h	e	e_1	e_2	e_3	e_4	e_R	L	LC	L_1	k	v	w	y	y_1
mm	max	0.60	0.10	0.35	7.1	4.50	7.1	4.50	0.5	4	5.5	4	5.5	0.5	0.35	0.35	0.125	0.45	0.07	0.05	0.08	0.1
	nom	0.55	0.07	0.30	7.0	4.45	7.0	4.45							0.30	0.30	0.075	0.40				
	min	0.50	0.05	0.25	6.9	4.40	6.9	4.40							0.25	0.25	0.025	0.35				

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT1066-1	- - -	- - -	- - -			~~08-02-13~~ 08-02-25

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